

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUN HSIUNG TSAI	08/23/2015
SHENG-WEN YU	08/24/2015
DE-WEI YU	08/26/2015
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN ROAD 6,
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14536298
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DATE SIGNED:	09/12/2015
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, we,

- (1) Chun Hsiung Tsai of No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu 300-77, Taiwan, R.O.C.
- (2) Sheng-Wen Yu of No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu 300-77, Taiwan, R.O.C.
- (3) De-Wei Yu of No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu 300-77, Taiwan, R.O.C.

have invented certain improvements in

SYSTEMS AND METHODS FOR SEMICONDUCTOR DEVICE PROCESS DETERMINATION USING REFLECTIVITY MEASUREMENT

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
X _____ filed on November 7, 2014 and assigned application number 14/536,298; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal

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proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chun Hsiung Tsai

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Dated: 08/23/2015

Chun Hsiung Tsai
Inventor Signature

Inventor Name: Sheng-Wen Yu

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Dated: 08/24/2015

Sheng-Wen Yu
Inventor Signature

Inventor Name: De-Wei Yu

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Dated: 08/26/2015

De-Wei Yu
Inventor Signature
